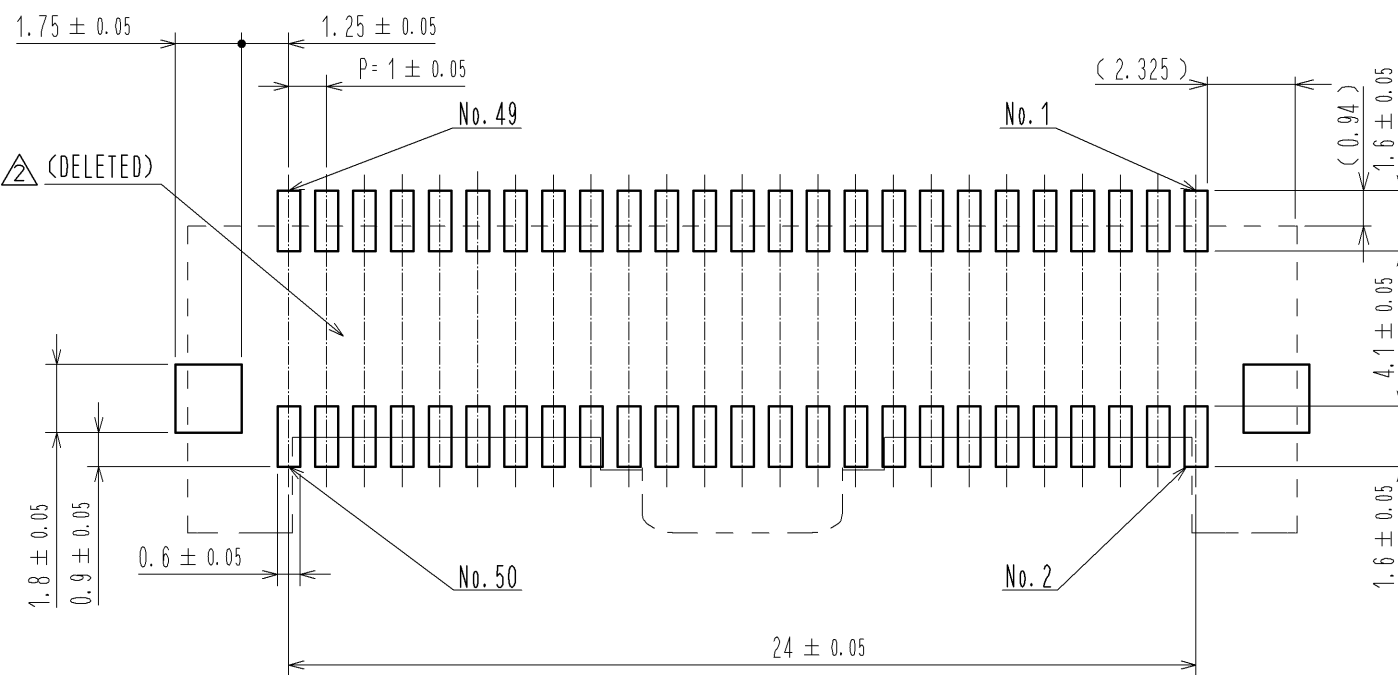


NOTE 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX
 2. (DELETED)
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MONUTED TO FPC.

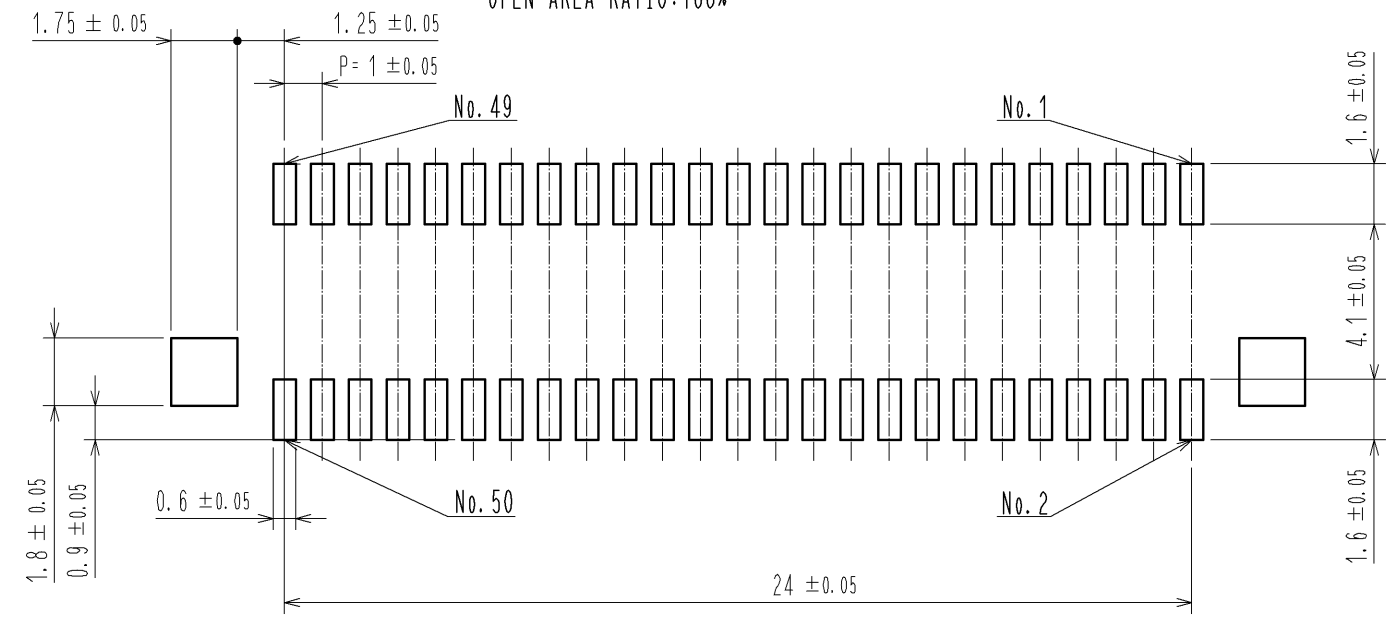
3	BRASS	CONTACT AREA : Au PLATING 0.05 μm MIN LEAD AREA : Au PLATING 0.05 μm MIN UNDER PLATING : Ni PLATING 1 μm MIN	8	PS	REEL, BLACK
			7	POLYESTER	CLEAR
2	BRASS	CONTACT AREA : Au PLATING 0.05 μm MIN LEAD AREA : Au PLATING 0.05 μm MIN UNDER PLATING : Ni PLATING 1 μm MIN	6	PS	CLEAR
			5	STAINLESS STEEL	—
1	LCP	BLACK, UL94V-0	4	BRASS	CONTACT AREA : Sn PLATING 1 μm MIN UNDER PLATING : Ni PLATING 0.5 μm MIN
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS
UNITS mm		SCALE 5 : 1	COUNT 2	DESCRIPTION OF REVISIONS DIS-H-008701	
APPROVED : KI. AKIYAMA 11.11.26			DESIGNED	MI. SAKIMURA	
CHECKED : OM. MIYAMOTO 11.11.26			CHECKED	TS. KUMAZAWA	
DESIGNED : TT. OHSAKO 11.11.26			DATE	14.04.22	
DRAWN : TT. OHSAKO 11.11.26			DRAWING NO. EDC3-330489-01		
HIROSE ELECTRIC CO., LTD.			PART NO. DF50-50DP-1H(51)		
			CODE NO. CL665-0013-7-51		
			1/3		

RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)

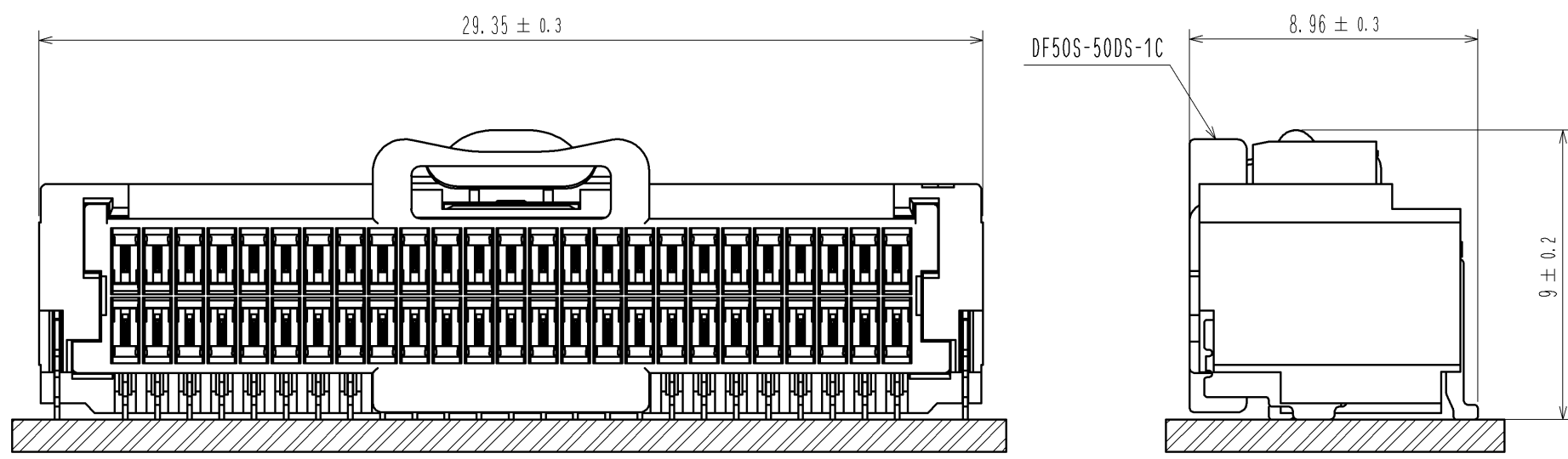


RECOMMENDED METAL MASK (FREE)

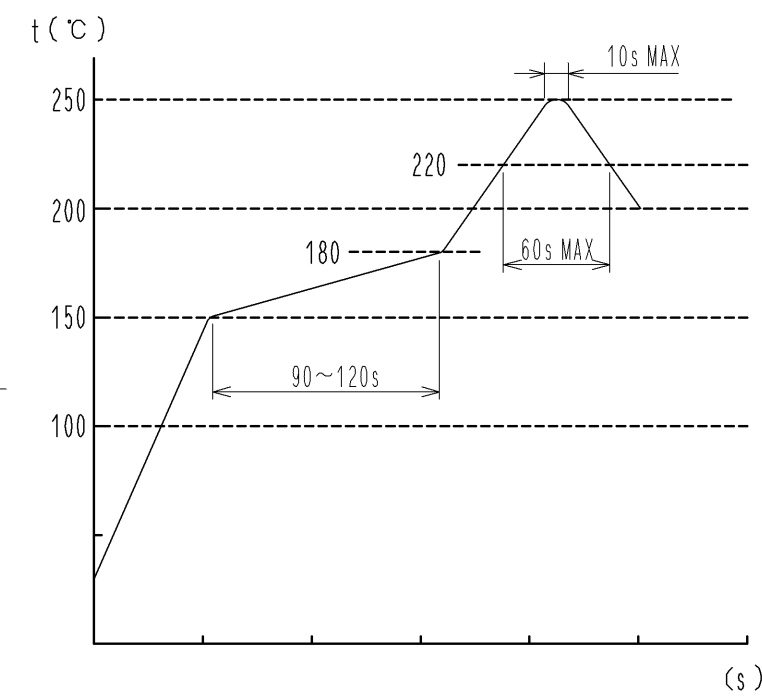
THICKNESS : 0.1mm
OPEN AREA RATIO:100%



MATING FIGURE (5 : 1)



REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MEASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING MATERIAL etc..

HRS	DRAWING NO.	EDC3-330489-01
	PART NO.	DF50-50DP-1H(51)
	CODE NO.	CL665-0013-7-51
		2/3

